PCN Number:	20190304004	PCN Date:	March 6 2019
Title:	Datasheet for DS90UB929-Q1 and DS90UH929-Q1		
Customer Contact:	PCN Manager	**Dept:**	Quality Services

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.

Texas Instruments

DS90UB929-Q1

SNLS457A – NOVEMBER 2014 – REVISED MARCH 2019

The datasheet number will be changing.

Device Family	Change From:	Change To:
DS90UB929-Q1	SNLS457	SNLS457A
DS90UH929-Q1	SNLS458	SNLS458A

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/DS90UB929-Q1

http://www.ti.com/product/DS90UH929-Q1

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

DS90UB929TRGCRQ1	DS90UB929TRGCTQ1	DS90UH929TRGCRQ1	DS90UH929TRGCTQ1

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com